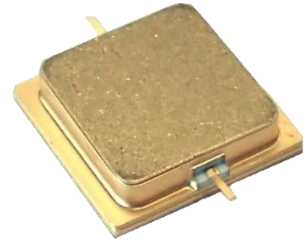


■ Features

- High Output Power: $P_{\text{sat}}=55.3\text{dBm}$ (Typ.)
- High Gain: $G_p=9.3\text{dB}$ (Typ.)
- High Power Added Efficiency: $\text{PAE}=38\%$ (Typ.)
- Broad Band: 9.0 to 10.0GHz
- Impedance Matched $Z_{\text{in}}/Z_{\text{out}} = 50\text{ohm}$
- Hermetically Sealed Package
- Long pulse operation *

*Reduced V_{ds} and/or low case temperature are needed to keep T_{ch} below 200 deg.C. Please contact for the detail.



■ Description

The SGC0910-301B-R is a high power GaN-HEMT that is internally matched for X-band radar bands to provide optimum power and gain in a 50ohm system.

ABSOLUTE MAXIMUM RATING (Case Temperature $T_c=25\text{ deg.C}$)

Item	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	55	V
Gate-Source Voltage	V_{GS}	-15	V
Storage Temperature	T_{stg}	-55 to +125	deg.C
Channel Temperature	T_{ch}	+250	deg.C

RECOMMENDED OPERATING CONDITION

Item	Symbol	Condition	Limit	Unit
Drain-Source Voltage	V_{DS}		≤ 50	V
Forward Gate Current	I_{GF}	$R_g=10\text{ohm}$	≤ 187.2	mA
Reverse Gate Current	I_{GR}	$R_g=10\text{ohm}$	≥ -13.6	mA
Channel Temperature	T_{ch}		$< +200$	deg.C
Output Power	P_{out}		$\leq P_5\text{dB}$	dBm

ELECTRICAL CHARACTERISTICS (Case Temperature $T_c=25\text{ deg.C}$)

Item	Symbol	Condition	Limit			Unit
			Min.	Typ.	Max.	
Pinch-off Voltage	V_p	$V_{\text{DS}}=50\text{V}$, $I_{\text{DS}}=20.0\text{mA}$	-	-4.5	-	V
Frequency Range	Freq.	$V_{\text{DS}}=50\text{V}$	9.0	-	10.0	GHz
Output Power *1	P_{sat}	$I_{\text{DS(DC)}}=1.0\text{A}$	54.3	55.3	-	dBm
Output Power *2	P_{sat}	Pulse Width=100μsec.	53.7	54.7	-	dBm
Power Gain *1	G_p	Duty=10%	8.3	9.3	-	dB
Power Gain *2	G_p	*1:f=9.0 to 9.6GHz	7.7	8.7	-	dB
Drain Current	I_{DSR}	*2:f=9.6 to 10.0GHz	-	15.8	18.4	A
Power Added Efficiency	PAE	Pin=46dBm	-	38	-	%
Thermal Resistance	R_{th}	Channel to Case ($P_{\text{diss}}=100\text{W}$, CW)	-	0.7	0.8	deg.C/W

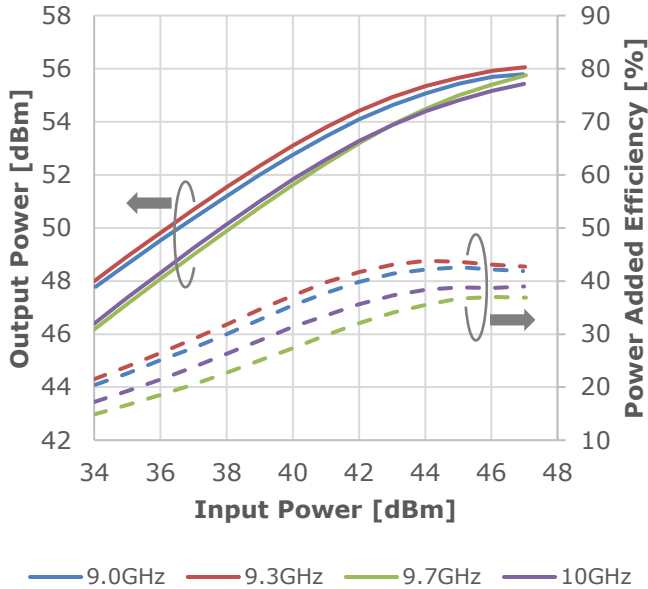
CASE STYLE	I2K	
RoHS Compliance	YES	
ESD	Class 2	2000V to <4000V

Note: Based on ANSI/ESDA/JEDEC JS-001-2012(C=100pF, R=1.5kohm)

RF Characteristics

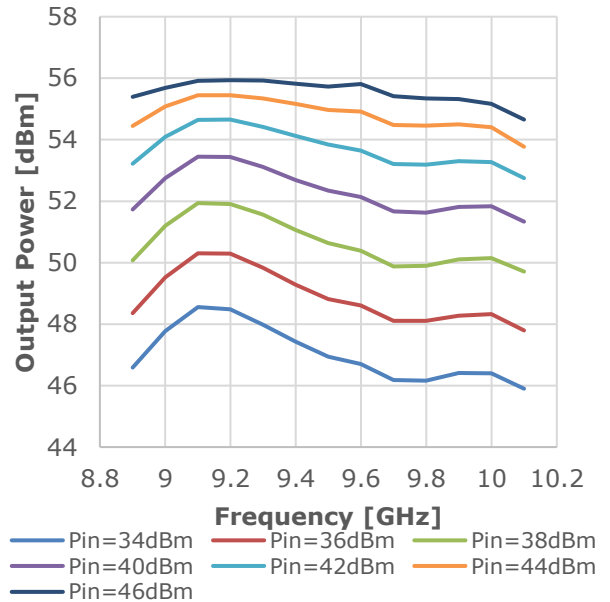
Output Power & Power Added Efficiency vs. Input Power

$V_{DS}=50V$, $I_{DS(DC)}=1.0A$
 $PW=100\mu sec.$, Duty=10%



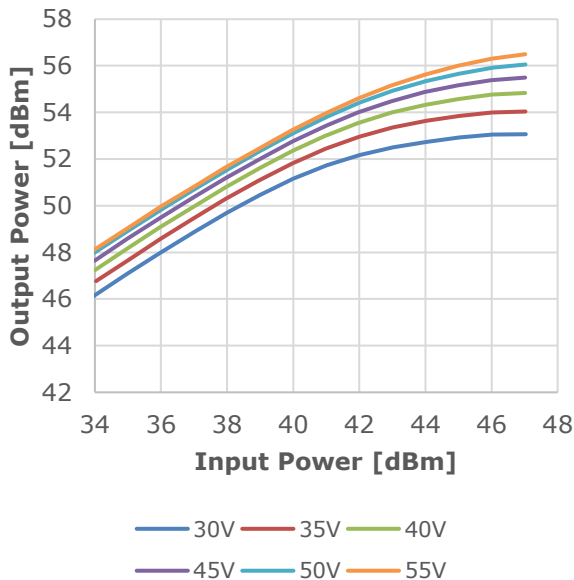
Output Power vs. Frequency

$V_{DS}=50V$, $I_{DS(DC)}=1.0A$
 $PW=100\mu sec.$, Duty=10%



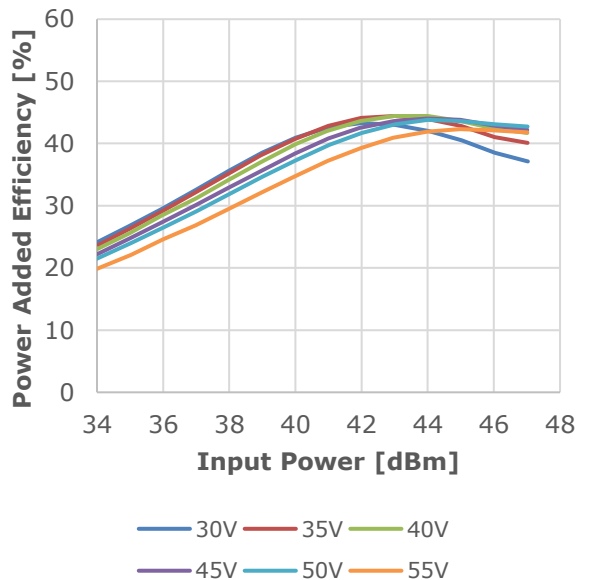
Output Power vs. Input Power by Drain Voltage

$f=9.3GHz$, $I_{DS(DC)}=1.0A$
 $PW=100\mu sec.$, Duty=10%



Drain Efficiency vs. Input Power by Drain Voltage

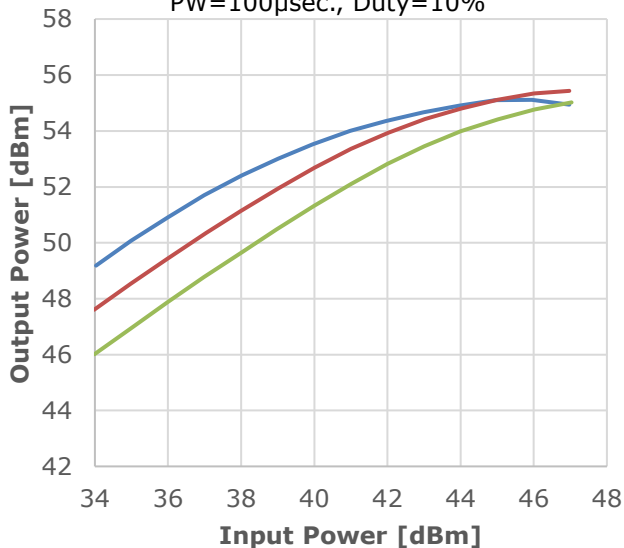
$f=9.3GHz$, $I_{DS(DC)}=1.0A$
 $PW=100\mu sec.$, Duty=10%



● RF Characteristics

**Output Power vs. Input Power
by case temperature**

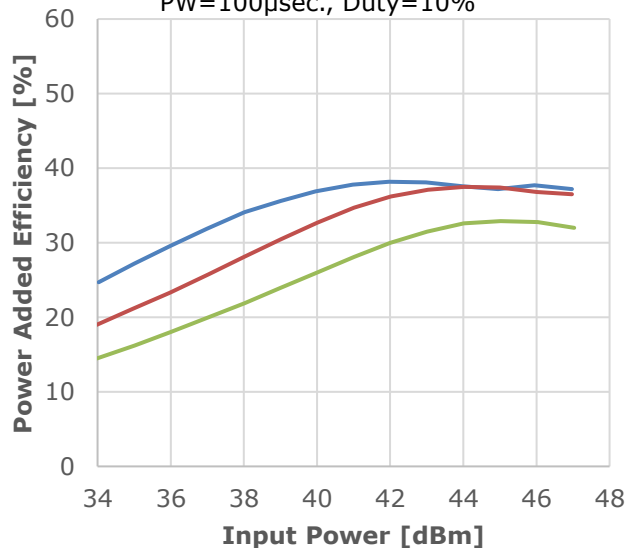
$f=9.3\text{GHz}$, $V_{DS}=50\text{V}$, $I_{DS(DC)}=1.0\text{A}$
 $PW=100\mu\text{sec.}$, Duty=10%



— -40deg.C — 25deg.C — 85deg.C

**Power Added Efficiency vs. Input Power
by case temperature**

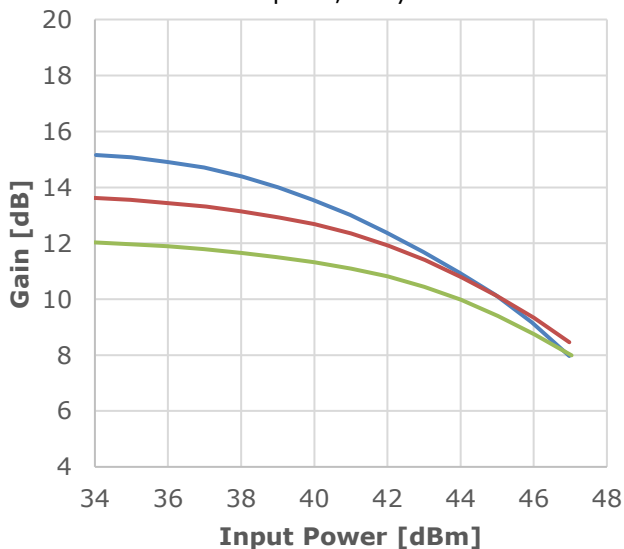
$f=9.3\text{GHz}$, $V_{DS}=50\text{V}$, $I_{DS(DC)}=1.0\text{A}$
 $PW=100\mu\text{sec.}$, Duty=10%



— -40deg.C — 25deg.C — 85deg.C

**Gain vs. Input Power
by case temperature**

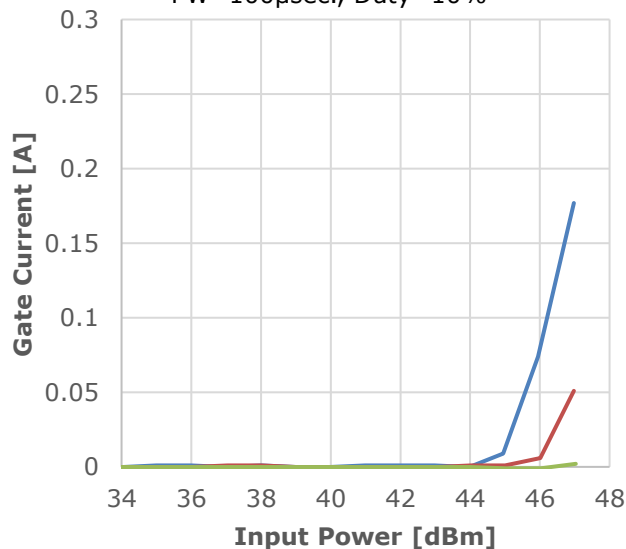
$f=9.3\text{GHz}$, $V_{DS}=50\text{V}$, $I_{DS(DC)}=1.0\text{A}$
 $PW=100\mu\text{sec.}$, Duty=10%



— -40deg.C — 25deg.C — 85deg.C

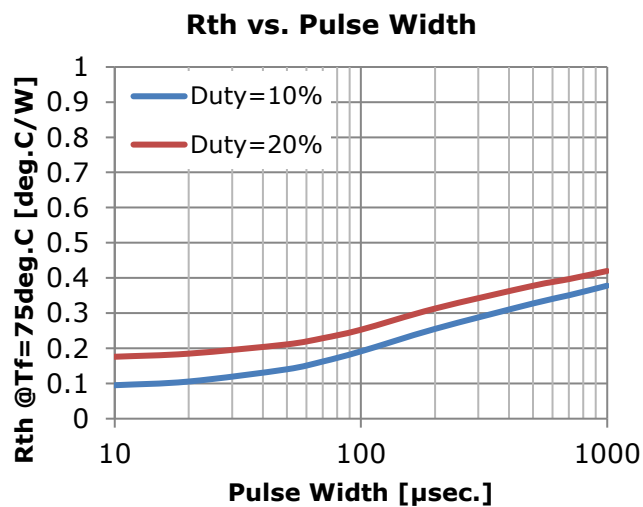
**Gate Current vs. Input Power
by case temperature**

$f=9.3\text{GHz}$, $V_{DS}=50\text{V}$, $I_{DS(DC)}=1.0\text{A}$
 $PW=100\mu\text{sec.}$, Duty=10%



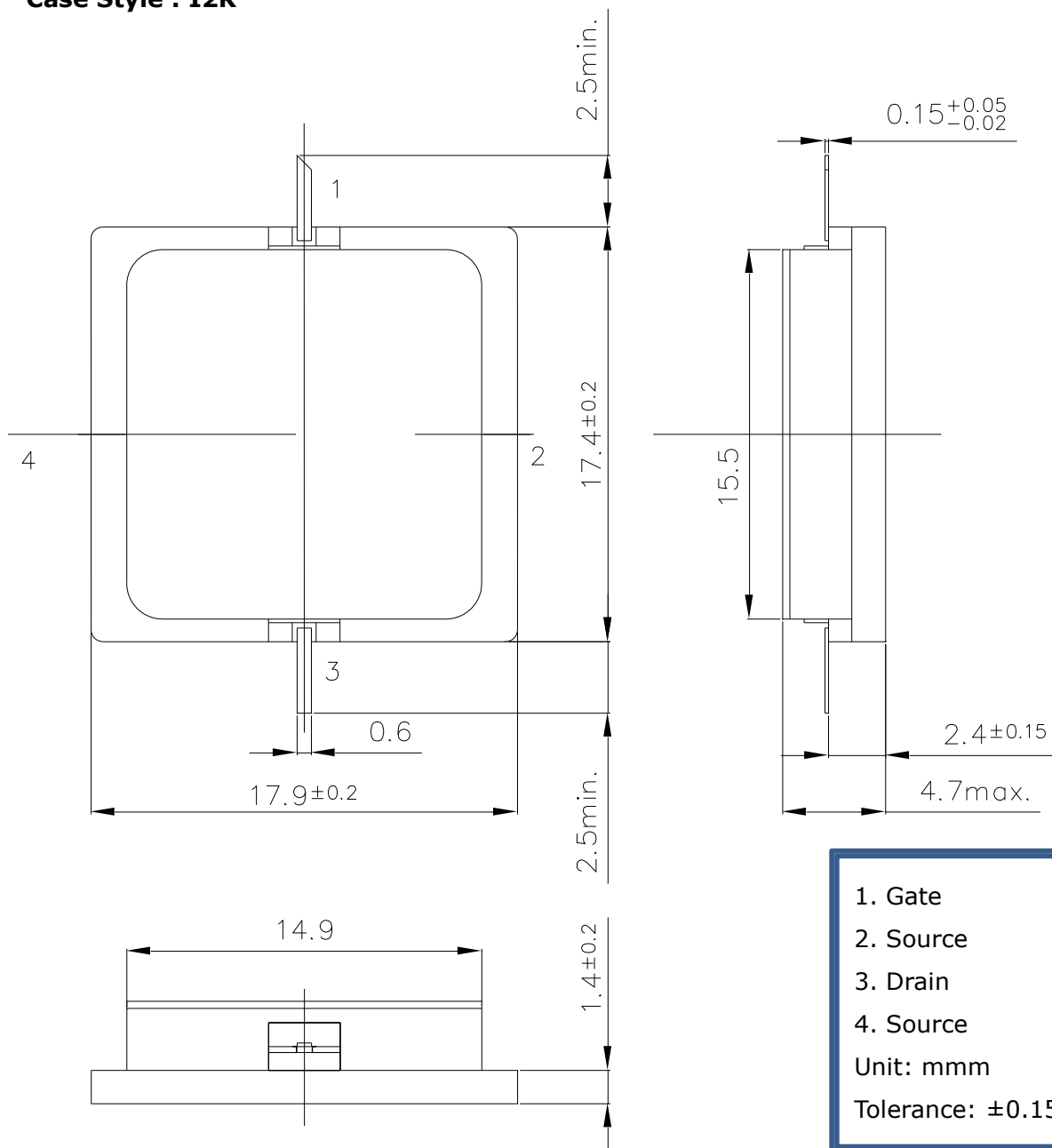
— -40deg.C — 25deg.C — 85deg.C

- Thermal Characteristics In Pulsed Operation

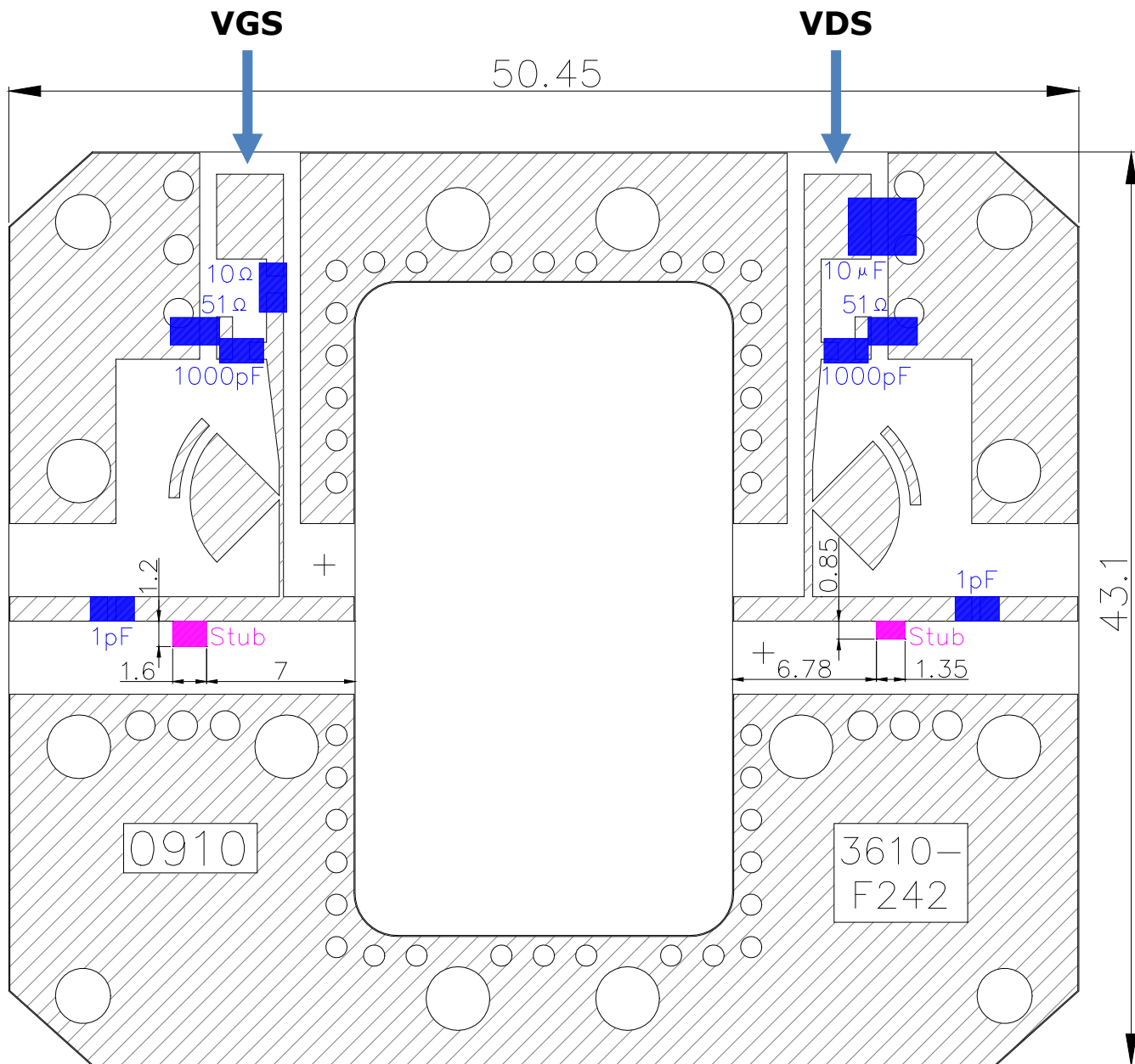


● **Package Outline**

Case Style : I2K



● Test Fixture



PCB : RO4003C H=0.5mm $\epsilon_r=3.55$ Cu=18μm
Unit : mm

For Safety, Observe the Following Procedures Environmental Management

- Do not put this product into the mouth.
- Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by-products are dangerous to the human body if inhaled, ingested, or swallowed.
- Respect all applicable laws of the country when discarding this product.
This product must be disposed in accordance with methods specified by applicable hazardous waste procedures.

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